

Product Summary

BV _{DSS}	R _{DS(ON)}	I _D T _A = +25°C
-20V	750mΩ @ V _{GS} = -4.5V	-0.6A
	1050mΩ @ V _{GS} = -2.5V	-0.5A
	1500mΩ @ V _{GS} = -1.8V	-0.45A

Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, which makes it ideal for high-efficiency power management applications.

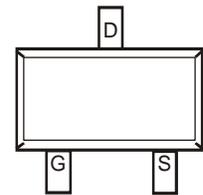
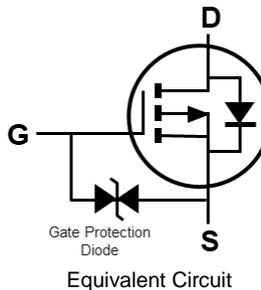
- DC-DC Converters
- Load Switch
- Power Management Functions



SOT323



Top View



Top View

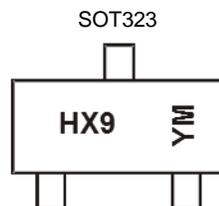
Gate Protection Diode

Ordering Information (Note 4)

Part Number	Case	Packaging
DMP2900UW-7	SOT323	3000/Tape & Reel
DMP2900UW-13	SOT323	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



HX9 = Product Type Marking Code
 YM = Date Code Marking
 Y or Y = Year (ex: G = 2019)
 M = Month (ex: 9 = September)

Date Code Key

Year	2018	2019	2020	2021	2022	2023	2024	2025
Code	F	G	H	I	J	K	L	M

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	-20	V
Gate-Source Voltage			V _{GSS}	±6	V
Continuous Drain Current (Note 6) V _{GS} = -4.5V	Steady State	T _A = +25°C	I _D	-0.6	A
		T _A = +70°C		-0.5	
Maximum Body Diode Forward Current (Note 6)			I _S	-0.45	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I _{DM}	-2.5	A

Thermal Characteristics

Characteristic			Symbol	Value	Unit
Total Power Dissipation (Note 5)			P _D	0.3	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State		R _{θJA}	393	°C/W
Total Power Dissipation (Note 6)			P _D	0.5	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State		R _{θJA}	272	°C/W
Operating and Storage Temperature Range			T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	-20	—	—	V	V _{GS} = 0V, I _D = -250µA	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	—	—	-100	nA	V _{DS} = -20V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	—	—	±2.0	µA	V _{GS} = ±4.5V, V _{DS} = 0V	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	-0.5	—	-1.0	V	V _{DS} = V _{GS} , I _D = -250µA	
Static Drain-Source On-Resistance	R _{DS(ON)}	—	—	0.75	Ω	V _{GS} = -4.5V, I _D = -430mA	
				1.05			V _{GS} = -2.5V, I _D = -300mA
				1.5			V _{GS} = -1.8V, I _D = -150mA
Diode Forward Voltage	V _{SD}	—	—	-1.2	V	V _{GS} = 0V, I _S = -150mA	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{ISS}	—	49	—	pF	V _{DS} = -16V, V _{GS} = 0V, f = 1.0MHz	
Output Capacitance	C _{OSS}	—	12	—	pF		
Reverse Transfer Capacitance	C _{RSS}	—	3.4	—	pF		
Total Gate Charge	Q _g	—	0.7	—	nC	V _{GS} = -4.5V, V _{DS} = -10V, I _D = -250mA	
Gate-Source Charge	Q _{GS}	—	0.1	—	nC		
Gate-Drain Charge	Q _{gd}	—	0.1	—	nC		
Turn-On Delay Time	t _{D(ON)}	—	5.3	—	ns	V _{DD} = -10V, V _{GS} = -4.5V, R _L = 47Ω, R _G = 10Ω, I _D = -200mA	
Turn-On Rise Time	t _R	—	2.8	—	ns		
Turn-Off Delay Time	t _{D(OFF)}	—	1247	—	ns		
Turn-Off Fall Time	t _F	—	445	—	ns		
Reverse Recovery Time	t _{RR}	—	10.5	—	ns	I _F = -1.0A, di/dt = 100A/µs	
Reverse Recovery Charge	Q _{RR}	—	1.8	—	nC		

- Notes:
- Device mounted on FR-4 substrate PCB, 2oz copper, with minimum recommended pad layout.
 - Device mounted on FR-4 substrate PCB, 2oz copper, with 1inch square copper plate.
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to production testing.

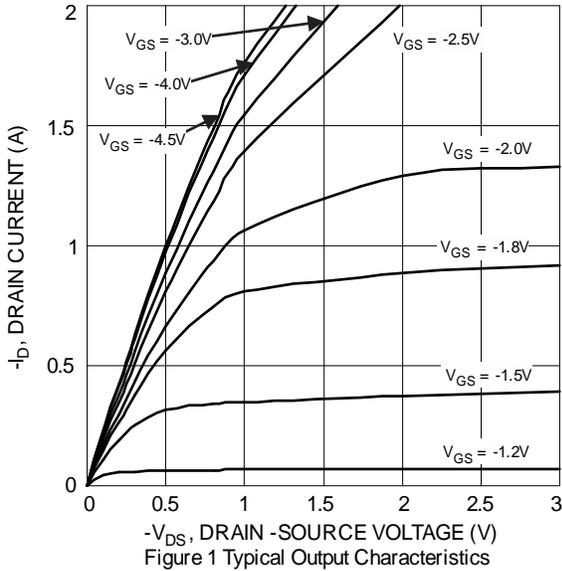


Figure 1 Typical Output Characteristics

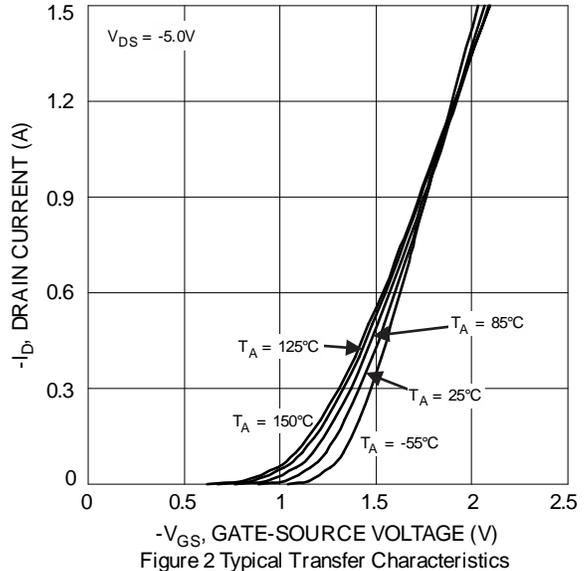


Figure 2 Typical Transfer Characteristics

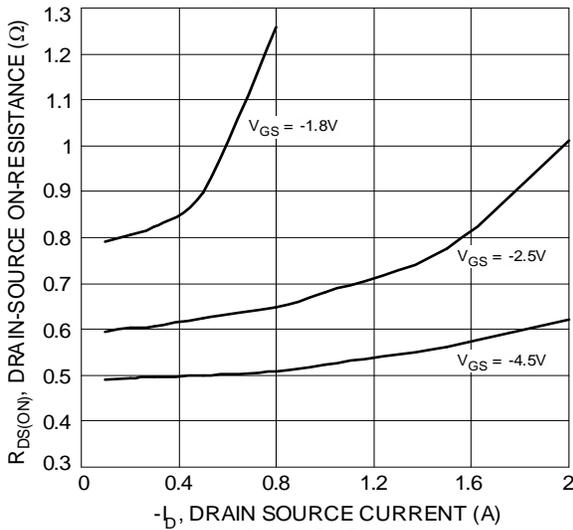


Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

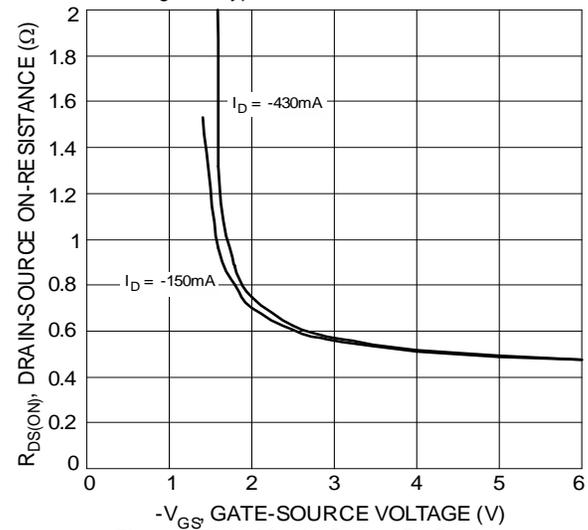


Figure 4 Typical Drain-Source On-Resistance vs. Gate-Source Voltage

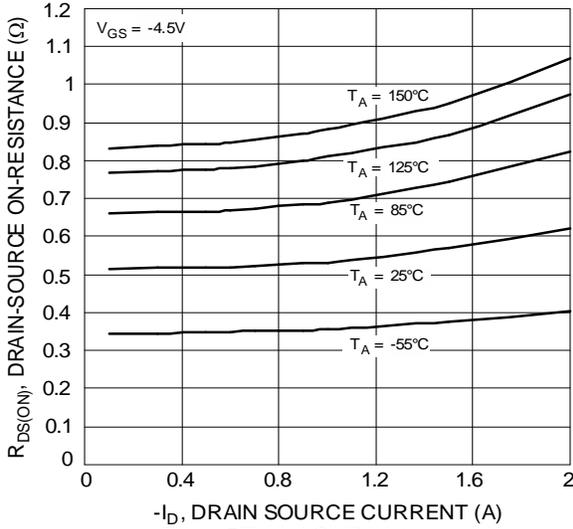


Figure 5 Typical On-Resistance vs. Drain Current and Temperature

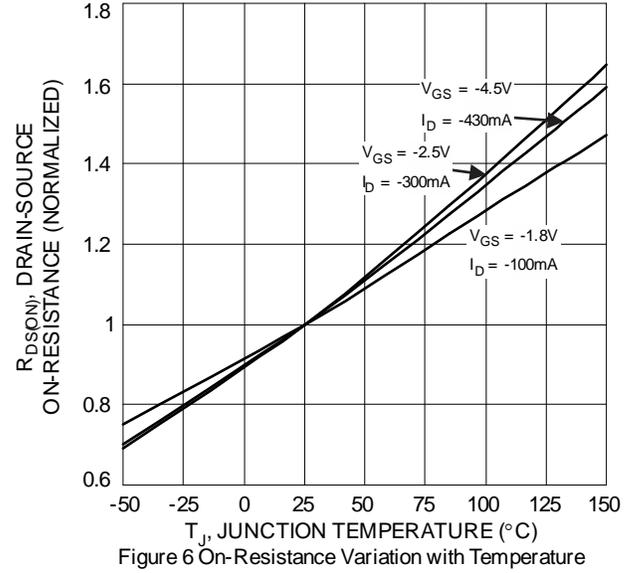


Figure 6 On-Resistance Variation with Temperature

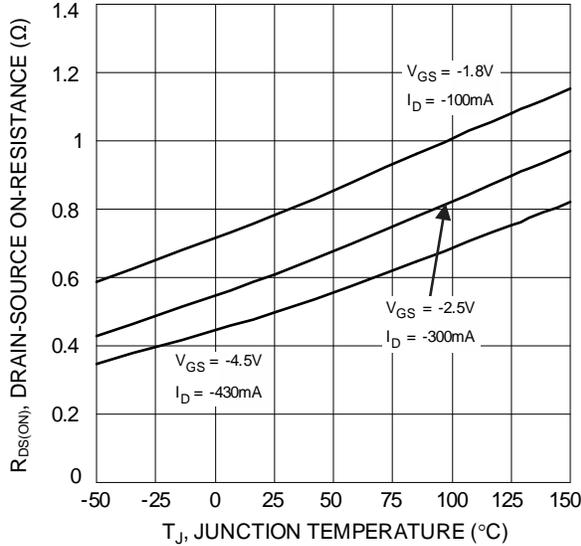


Figure 7 On-Resistance Variation with Temperature

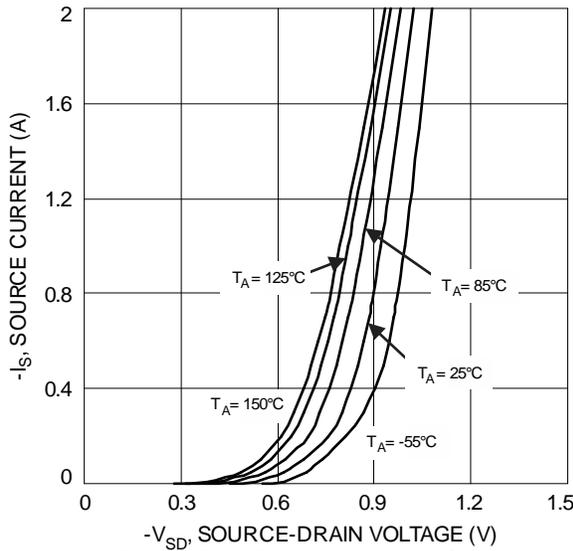


Figure 9 Diode Forward Voltage vs. Current

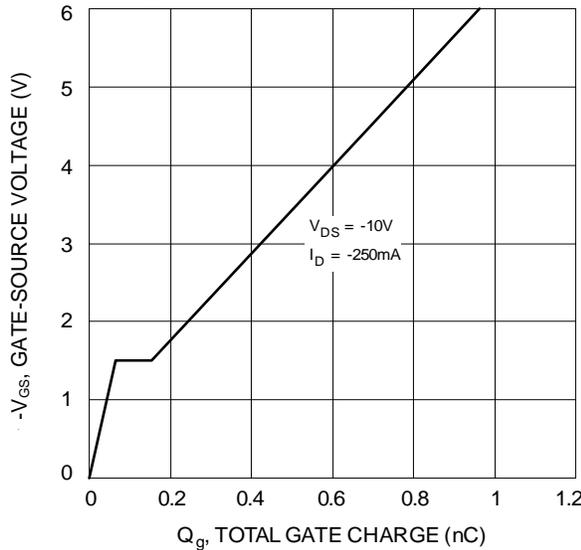


Figure 11 Gate Charge

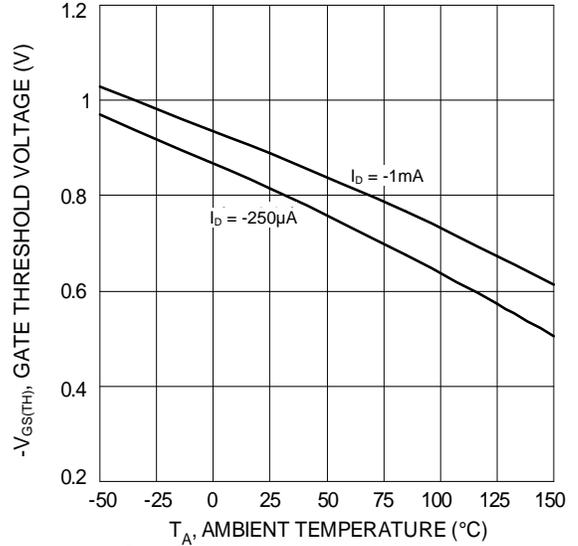


Figure 8 Gate Threshold Variation vs. Ambient Temperature

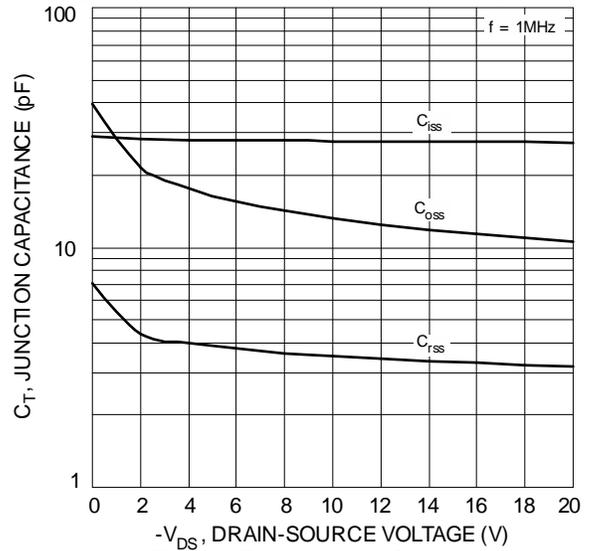


Figure 10 Typical Junction Capacitance

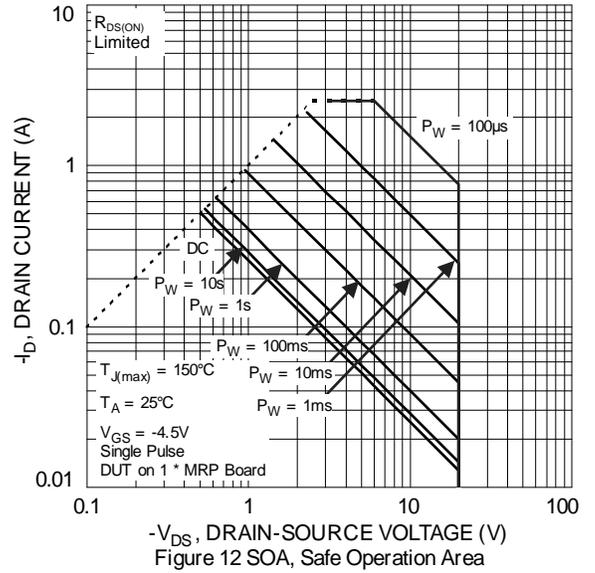
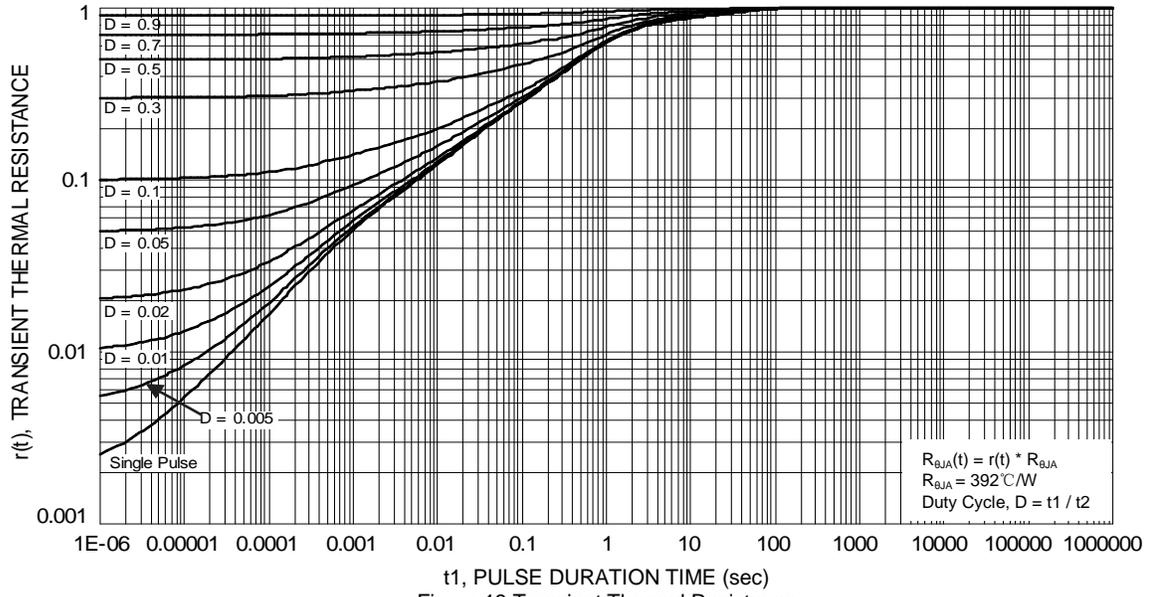


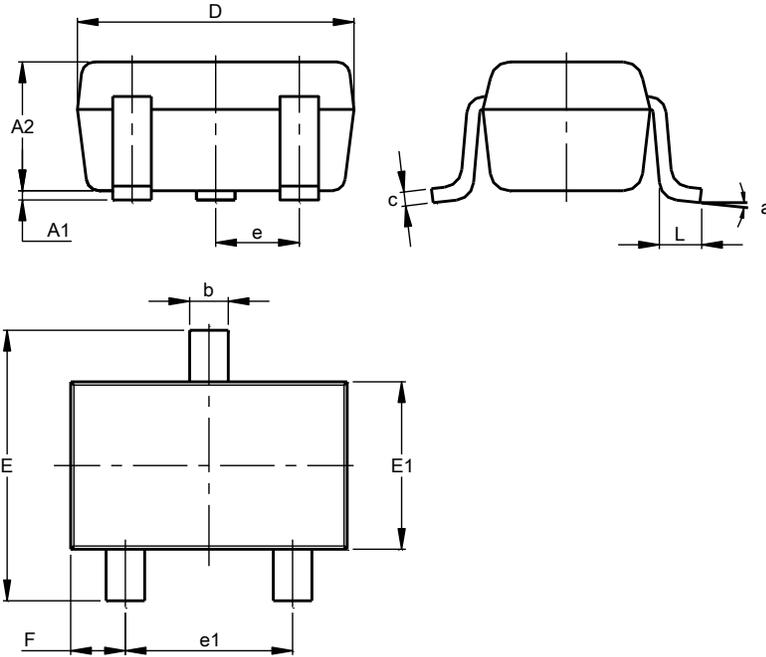
Figure 12 SOA, Safe Operation Area



Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

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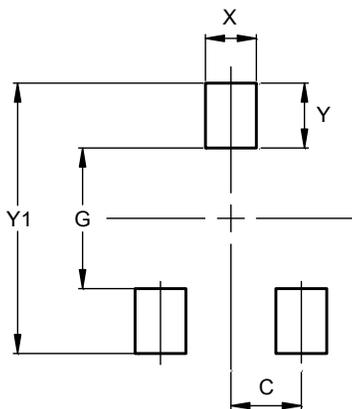


SOT323			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.90	1.00	0.95
b	0.25	0.40	0.30
c	0.10	0.18	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
e1	1.20	1.40	1.30
F	0.375	0.475	0.425
L	0.25	0.40	0.30
a	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT323



Dimensions	Value (in mm)
C	0.650
G	1.300
X	0.470
Y	0.600
Y1	2.500

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